Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (currently amended) A composition comprising the product obtained by blending to homogeneity:

(A) 100 parts by weight of a polyorganosiloxane containing at least two alkenyl radicals per molecule;

(B) an organohydrogensiloxane containing at least two silicon-bonded hydrogen atoms in each molecule, in a quantity sufficient to provide from 0.5 to 3 silicon-bonded hydrogen atoms per alkenyl radical in ingredient (A);

(C) from 50 to 2,000 parts by weight of finely divided silver particles pre-treated with ~~an organosilicon compound selected from the group consisting of (i) silanes containing at least one alkoxy group and~~ (ii) a silanol endblocked siloxane oligomer~~organosiloxanes~~;

(D) an amount sufficient to promote curing of said composition of a platinum catalyst;

(E) up to 20 weight percent, based on the weight of component (A), of ingredient (E), an organosilicon compound containing at least one silicon-bonded alkoxy group per molecule; and

(F) 0.001 to 5 weight parts, per 100 weight parts of ingredient (A), of a cure inhibitor.

2. (canceled).

3. The composition of claim 1, where component (C)(ii) comprises a siloxane oligomer selected from the group consisting of:

(a) a silanol endblocked dimethylsiloxane oligomer,

(b) a silanol endblocked dimethylsiloxane/methylvinylsiloxane co-oligomer,

(c) a silanol endblocked methylvinylsiloxane oligomer,

(d) a silanol endblocked methylphenylsiloxane oligomer, and

(e) a mixture thereof.

4.-6. (canceled).

7. (new) The composition of claim 1, where component (A) comprises:

a polyorganosiloxane polymer selected from trimethylsiloxy- endblocked dimethylsiloxane/methylvinylsiloxane copolymer, trimethylsiloxy-endblocked polymethylvinylsiloxane,

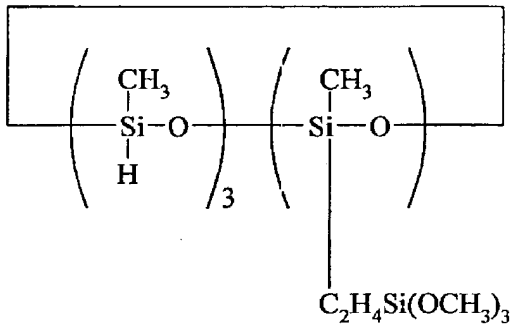
trimethylsiloxy-endblocked methylvinylsiloxane/ methylphenylsiloxane copolymer, trimethylsiloxy-endblocked dimethylsiloxane/methylvinylsiloxane/methylphenylsiloxane copolymer, dimethylvinylsiloxy-endblocked polydimethylsiloxane, dimethylvinylsiloxy-endblocked polymethylvinylsiloxane, dimethylvinylsiloxy-endblocked polymethylphenylsiloxane, dimethylvinylsiloxy-endblocked dimethylsiloxane/methylvinylsiloxane copolymer, dimethylvinylsiloxy-endblocked dimethylsiloxane/methylphenylsiloxane copolymer, silanol-endblocked dimethylsiloxane/methylvinylsiloxane copolymer, silanol-endblocked polymethylvinylsiloxane, and silanol-endblocked dimethylsiloxane/methylvinylsiloxane/methylphenylsiloxane copolymer;

an alkenyl-substituted organosiloxane resin selected from resins composed of the combination $R_3SiO_{1/2}$ and $SiO_{4/2}$ units, the $RSiO_{3/2}$ unit alone, the combination of R_2SiO and $RSiO_{3/2}$ units, the combination of R_2SiO, $RSiO_{3/2}$ and $SiO_{4/2}$ units, and mixtures containing two or more of these resins, where each R is independently a substituted or unsubstituted monovalent hydrocarbon group, with the proviso that at least one of the R groups represents an alkenyl radical;

or a mixture thereof.

8. (new) The composition of claim 1, where component (B) comprises: trimethylsiloxy-endblocked polymethylhydrogensiloxane, trimethylsiloxy-endblocked dimethylsiloxane/methylhydrogensiloxane copolymer, trimethylsiloxy-endblocked methylhydrogensiloxane/methylphenylsiloxane copolymer, trimethylsiloxy-endblocked dimethylsiloxane/methylhydrogensiloxane/methylphenylsiloxane copolymer, dimethylhydrogensiloxy-endblocked polydimethylsiloxane, dimethylhydrogensiloxy-endblocked polymethylhydrogensiloxane, dimethylhydrogensiloxy-endblocked dimethylsiloxane/methylhydrogensiloxane copolymer, dimethylhydrogensiloxy-endblocked dimethylsiloxane/methylphenylsiloxane copolymer, dimethylhydrogensiloxy-endblocked polymethylphenylsiloxane, silanol-endblocked polymethylhydrogensiloxane, silanol-endblocked dimethylsiloxane/methylhydrogensiloxane copolymer, silanol-endblocked methylhydrogensiloxane/methylphenylsiloxane copolymer, or silanol-endblocked dimethylsiloxane/methylhydrogensiloxane/methylphenylsiloxane copolymer.

9. (new) The composition of claim 1, where component (B) comprises:



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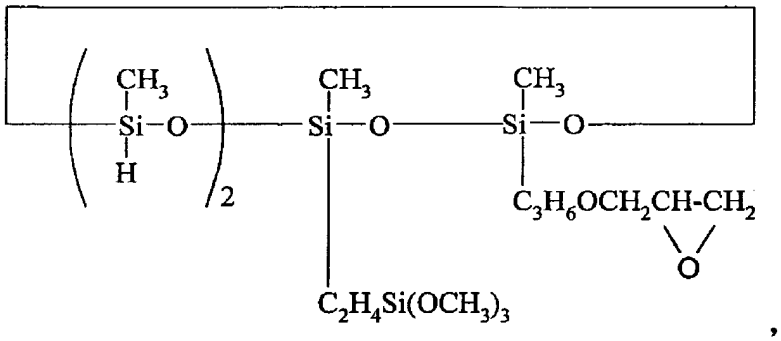

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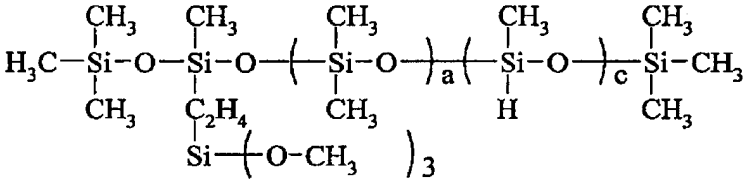

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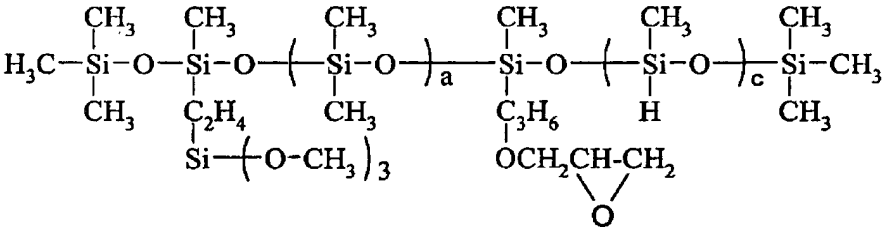
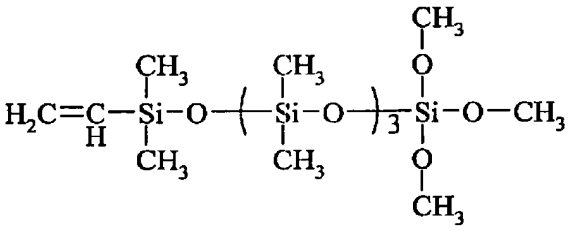


where a represents an integer with a value of at least 1, and c represents an integer with a value of at least 2.

10. (new) The composition of claim 1, where ingredient (D) comprises: platinum black, platinum supported on powdered alumina, platinum supported on powdered silica, platinum supported on powdered carbon, chloroplatinic acid, an alcohol solution of chloroplatinic acid, a chloroplatinic acid/olefin complex, a chloroplatinic acid/vinylsiloxane complex, or a platinum catalyst dispersed in a microparticulate form of thermoplastic organic resin.

11. (new) The composition of claim 8, where ingredient (E) comprises: an alkoxysilane or an organosilicon compound; where the alkoxysilane is selected from tetramethoxysilane, tetraethoxysilane, dimethyldimethoxysilane, methylphenyldimethoxysilane, methylphenyldiethoxysilane, phenyltrimethoxysilane, methyltrimethoxysilane, methyltriethoxysilane, vinyltrimethoxysilane, allyltrimethoxysilane, allyltriethoxysilane, 3-glycidoxypropyltrimethoxysilane, or 3-methacryloxypropyltrimethoxysilane; and the organosilicon compound is selected from



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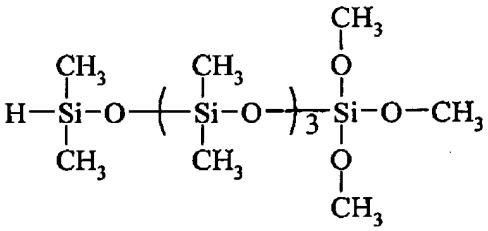

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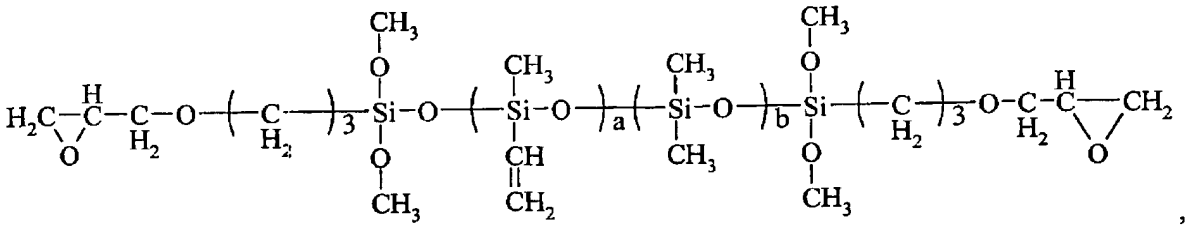
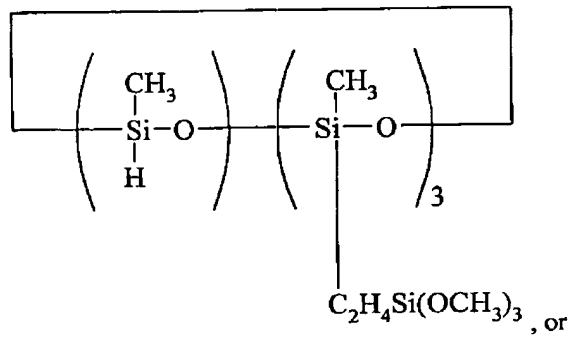
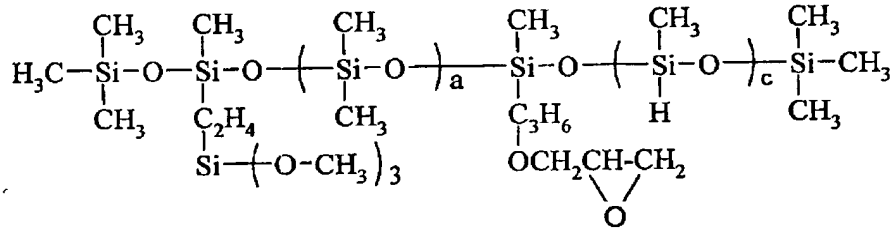


where a and b are each integers with values of at least 1





where a is an integer with a value of at least 1 and c is 0 or 1.

12. (new) The composition of claim 9, where ingredient (E) comprises an organosilicon compound that contains silicon-bonded alkoxy groups and either 1 or no silicon-bonded hydrogen atoms.

13. (new) The composition of claim 1, where ingredient (F) comprises an alkynyl alcohol, an ene-yne compound, 1,3,5,7-tetramethyl-1,3,5,7-tetravinylcyclotetra-siloxane, 1,3,5,7-tetramethyl-1,3,5,7-tetrahexenylcyclotetra-siloxane, or benzotriazole.

14. (new) The composition of claim 1 further comprising: an inorganic filler selected from fumed silica, crystalline silica, calcined silica, wet-process silica, fumed titanium oxide, and carbon black; or the

inorganic filler whose surface has been treated with an organosilicon compound selected from an organoalkoxysilane, organochlorosilane, or an organodisilazane.

15. (new) A method comprising: coating the composition of claim 1 on a surface of a circuit board.